

**the
LYNX***November 2011***Table of Contents**

Upcoming Events	2
Reliability Physics Conference. 2	
Newsletter Inputs	2
About IEEE.	2
Member Discounts	3
Welcome New IEEE Members	3
Awards Dinner	4
Job Openings.	5
Advertising Section.	5
IEEE OC Student Design Contest	6
Tech Job Fair	7
Games Innovation Conference . 8	
Thermal Design and Modeling of IC Packages.	9
Components, Packaging and Manufacturing Technology Society.	12
Executive Officers.	13

IEEE/Orange County Website:
www.ieee.org/ocs

With thanks to our sponsors:

**The Chair's Corner:****by Alvin Joseph**

Greetings and hope you are all on track to deliver on the goals you set at the beginning of the year!

On October 29th, the IEEE Orange County Section held it's annual awards dinner. We honored the volunteers who served the section in 2010 and also the winners of the 2011 IEEE Orange County Section awards – Alain Chahwan from Western Digital Corporation who won the outstanding engineer award and Dr. Menas Kafatos from Chapman University who won the outstanding leadership award. Dr. Raman Unnikrishnan, Dean of the college of Engineering and Computer Science at CSUF delivered an enlightening and thought provoking presentaton on STEM education and the need to act on it now. Mathobotix (engineers4kidsusa) with whom we partnered this year in the Robotics and STEM education space demonstrated how they help to promote STEM education to middle school and high school kids. I'd like to take this opportunity to thank to all those who volunteer at IEEE Orange County Section. If do not volunteer yet and are interested in volunteering at the IEEE Orange County Section, please send me a quick note with your area of interest.

Here is the November Lynx OC section newsletter with updates on IEEE Orange County section activities and upcoming event information. November is a busy month with the Games Innovation conference, the IEEE annual Job fair and the IEEE OC annual student design contest in addition to the usual regularly scheduled seminars by the chapters. Please choose the events that are of interest to you and sign up soon. Also, let us know areas that you'd like to see more events on. This will help shape up our future programs.

As always, feel free to drop me a line at alvin@ieee.org. I'd love to hear from you on how the IEEE Orange County section can serve you better.

Happy Thanksgiving!

Alvin Joseph
Chairman, IEEE Orange County Section
www.ieee.org/ocs

The IEEE Orange County Upcoming Events

Nov 2
IEEE Student Design Contest
Radisson Hotel Newport Beach, CA
www.socconference.com/students.htm

Nov 2
IEEE Job Fair

Nov 2 - 4
International Games Innovation Conference
Chapman University, Orange, California
<http://ice-gic.ieee-cesoc.org/>

Nov 2-4
The Third IEEE International Games Innovation Conference
One University Drive, Chapman University, Orange, CA

Nov 15
Short Course on Thermal Design and Modeling of IC Packages
Henkel Electronic Materials, LLC
14000 Jamboree Road
Irvine, California

Dec 9
3-D Integrated Circuits: Technologies Enabling the Revolution
Jazz Semi Auditorium, Conexant Systems Inc.
4321 Jamboree Rd., Newport Beach, CA

If you'd like your event to be included, please email details to me@sharonforsberg.com

About the IEEE

The Institute of Electrical & Electronics Engineers [IEEE] is the leading organization for the advancement of technology. The IEEE is a 501(c)(3) non-profit, technical professional association of more than 390,000 individual members in over 175 countries. The IEEE Orange County Section serves over 3,700 members in Orange County in addition to the local community.

IEEE Orange County Section
P.O.Box 15264, Irvine, CA
92623-5264

IEEE Electron Devices Society and the IEEE Reliability Society to Sponsor Reliability Physics Conference

The IEEE EDS and Reliability societies are will co-sponsor the conference entitled "2012 IEEE International Reliability Physics Symposium (IRPS)". This conference will be held April 15-19, 2012 in Garden Grove, California, USA.

For further information, please contact,

David Barber
PO Box 2097
Banner Elk NC 28604 USA
Ph : +1 828 898 7001
Fax: +1 828 898 6379
dbarbsta@aol.com
or Conference Services Dept., at IEEE Operations Center at +1 732 562 3878

To IEEE Orange County Chapters:

Newsletter Inputs

As we begin a new year of activities, it is fitting to remind OC Chapters of the protocol to get their news items published in the Newsletter. Simply, e-mail your news item to info.at.nanomems-research.com no later than the 15th of the month, prior to the month whose Newsletter you are targeting. For example, if you want the February'09 Newsletter to contain your news item, please, submit it no later than January 15th, 2009. In your e-mail, please, enclose your news item between two lines of "+" characters, i.e.:

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                                     News Item Title
Newsletter content Newsletter content Newsletter content Newsletter content
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Thank you,
Hector J. De Los Santos
IEEE Orange County Section, Newsletter Editor
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Member Discounts

As you well know, IEEE members can take advantage of a myriad of discount opportunities, either in the form of core IEEE products OR from IEEE sponsored programs which are offered at reduced rates as a benefit of membership. However, member surveys indicate that awareness of IEEE discount programs is low, such that 50% of members do not know about them or where to find them.

To address this issue, a decision was made to present information about all these programs in a new centralized location, which is now the “IEEE Member Discounts” Web page. This notice also serves to announce that the brand “Financial Advantage Program” has been retired.

Please take a look at the new IEEE Member Discounts page: <http://www.ieee.org/go/discounts>.

The “IEEE product discounts” section is listed first and we are still working on compiling all the entries to appear here. The “IEEE sponsored discounts” section lists programs in the following categories: Insurance, Travel, Technology and Home/Office Discounts. Programs that are available globally are clearly marked in this listing. We have also added an FAQ page that seeks to clarify the geographic availability of the sponsored programs and how they are developed and vetted.

Welcome New IEEE members in Orange County!

We'd like to extend a warm welcome to the following new members:

Member	Grade	Member	Grade
		Matthew Thornton	
			Student Member
Wenpei Lin			
	Graduate Student Member	Amit Bhasin	Student Member
Reza Sharifi	Member	Hisu Heidi Park	Student Member
Jeremy Freeman	Member	David Mingdow Chou	
KATHY LE	Member		Student Member
Gunjana Sharma	Member	Ivan Leroy Hoffman	
Adam Oberbeck	Student Member		Student Member
Chung Wing Wu	Student Member	Leslie Wong	Student Member
melanie m baque	Student Member	Andrew Shih	Student Member
Ramzi Bassam Rabadi		Michael Black	Student Member
	Student Member	Ben Phung	Student Member
michael blank	Student Member	Eric Scott Emerson	
Alexander David Ramirez			Student Member
	Student Member	Walter Heth	Student Member
Vinci Enriquez Sevilla Jr.		David Van Workum	
	Student Member		Student Member
Gia Hoa Vu	Student Member		
William John Drewes			
	Student Member		



Awards Dinner



▲ Alain Chahwan – Outstanding engineer award (with Russel Hunter and Dr. David Cheng)

▼ Award for Western Digital (with Alvin Joseph and Dr. David Cheng)



▲ Dr. Menas Kafatos – Outstanding Leadership award (with Russel Hunter and Alvin Joseph)

▼ Dr Unnikrishnan, guest speaker for the evening



▲ Alvin Joseph (with Russell Hunter)

▼ Hector J. De Los Santos (with Russell Hunter and Alvin Joseph)



Naveen Reddy (with Russell Hunter) ▲

▼ Thomas Ha (with Russell Hunter and Alvin Joseph)



▲ Dr. David Cheng (with Russell Hunter and Alvin Joseph)

▼ Dr Shireesh Verma (with Russell Hunter and Alvin Joseph)



▼ Farhad Mafie (with Russell Hunter and Alvin Joseph)



▲ Ralph Hileman (with Russell Hunter and Alvin Joseph)



Derrick Lo (with Russell Hunter) ▲

▼ Russell Hunter (with Alvin Joseph and Dr. David Cheng)



▲ Enjoying the awards dinner

▼ Closing (Hector, Russell, Alvin)



Job Openings in OC

Optical Engineer

Job Summary:

Are you a **Senior Software Engineer** (Visual Studio, C#, .NET, SQL Server) whose hands-on technical and **team leadership, project management** career path should ultimately lead to being the principal software engineer for the R&D division of this stable \$1B+ household brand that enjoys a 100+ year history of international name recognition?

You will be THE Senior in-house Software Engineer and key member of a small, elite R&D team, responsible for the development of the next generation of software to replace a legacy system involved in the automated quality screening, packaging, and distribution processes of the most recognized agricultural brand name in the world.

The job is 50% heads-down coding and 50% heads-up project management, collaborating and interfacing with a 3rd party development team, and being the key technical liaison between major customers and corporate executives. Ideally, the successful person in this capacity will evolve into technical leader and mentor of a small, accountable and high-energy internal software development team.

You'll enjoy a great deal of autonomy working in a stable and long established corporate environment (near Ontario International Airport) that offers great benefits, unlimited career growth and the opportunity to be solely responsible for software strategy and technical leadership in what amounts to the capstone of a 20 year long transition process from being an Academic/Research environment into a cutting edge and innovative Profit Center of the corporation.

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If you or your company has a job to advertise, please send an email to shireesh@ieee.org with a concise description of the job and contact information. Depending on space availability, we will attempt to post the job opening in the IEEE Section newsletter and website.

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Your development background in any of the following industries may qualify you for this career-making unique opportunity: Artificial Intelligence (AI), Algorithms, Process Control, Document Automation, Image Processing, Programmable Logic Controls (PLC), Robotics, Manufacturing Automation, Security Appliances, or Vision/Optics/OCR/Video/Radar, I/O or related embedded systems.

This mission critical role will guide the software technology involved in the NEXT 100 years of this company's history, and be an integral part of a new technical leadership team that includes the Director of Engineering and a Division VP/GM who have joined the organization expressly for this purpose from the unrelated but relevant automated material handling systems industry.

For more information and immediate confidential consideration, contact:

Mark A. Bassett, CPC
SCVN Board of Directors

eNamix Inc.
emerging technology executive services

O: 949.502.4219

C: 949.395.7793

E: MarkB+at+eNamix+dot+com

Advertising Section in the Newsletter

Our Newsletter now includes an advertising section. For details on how to place your ad please send us e-mail at: info.at.nanomems-research.com

Hector J. De Los Santos
IEEE Orange County Section Newsletter Editor



ORANGE COUNTY SECTION

www.ieee.org/ocs

IEEE ORANGE COUNTY SECTION PRESENTS IEEE OC STUDENT DESIGN CONTEST (SDC)*

9th International System-on-Chip (SoC) Conference, Exhibit & Workshops
November 2 & 3, 2011 – Radisson Hotel Newport Beach

www.SoCconference.com

SPONSORED BY:



ENGINEERING & COMPUTER SCIENCE STUDENTS. . .

IEEE Orange County Section cordially invites you to participate in its 2011 **Student Design Contest (SDC)**! The Contest will be held on Wednesday, November 2, 2011, at the 9th International System-on-Chip (SoC) Conference Exhibit, at the Radisson Hotel Newport Beach.

The SDC provides an outstanding forum in which graduate and undergraduate students' efforts can be shared with an audience of academic and industrial technical experts.

SDC PROJECT PROPOSAL

The Student Design Contest is designed to encourage engineering and computer science undergraduates and graduates students to work on a new project and present their work at the 9th International System-on-Chip (SoC) Conference Exhibit to a group of judges from industry and academia.

Each project will be judged based on its overall complexity, originality, and completion of the work.

THE DESIGN PROJECTS COULD BE IN . . .

- Hardware Design
- Robotics
- Software Design
- Analog Design
- Digital Design
- EDA Tools
- Chip Design / SoC
- MEMS
- SOI vs. CMOS
- Optics
- Embedded platforms
- Graphics Sub-system
- Instrumentation
- Software Algorithms
- FPGA-Based Design
- Microcontroller-Based
- Embedded Systems
- Design Methodologies
- Detailed Technology Analysis/Research
- Bio-Engineering
- CPUs & DSPs
- Memory Design
- SSD
- I/O Sub-systems
- Web-Related Projects
- And Similar Topics . . .

**"WILD & CRAZY" DESIGN PROJECTS ARE ALSO WELCOMED!
WE LOOK FORWARD TO HEARING FROM YOU.**

Don't Miss Out!

**AN EXCELLENT OPPORTUNITY TO NETWORK & PROMOTE
YOUR ENGINEERING TALENT & EXPERTISE!**

DATES TO REMEMBER

(1) Monday, October 10, 2011: Deadline for submission of Design Contest Proposal/Abstract (1-2 paragraphs in MS Word) and your biography.
Submit to: SoC@SoCconference.com

(2) Friday, October 28, 2011: Deadline for submission of Final Report (in MS Word or PowerPoint).
Submit to: SoC@SoCconference.com

(3) Wednesday, November 2, 2011: Projects will be reviewed and winner will be announced at the 9th International SoC Conference Exhibit reception starting at 5:00 PM, at the Radisson Hotel Newport Beach.

PRIZES

(1) The first 30 students that submit their FINAL report/papers will receive a Western Digital Passport Hard Drive! You must be at the event on Nov 2, to receive your WD Hard Drive. No Exceptions!

(2) First Prize: \$500.00
Second Prize: \$300.00
Third Prize: \$200.00

(3) All participating students (who have submitted their Final Report) will receive a 2-Day Conference pass.

(4) Names and pictures of the winners will be displayed on the SoC Conference and IEEE OC Section websites.

CONTEST RULES

- Final Report format must be in MS Word or PowerPoint.
- Poster size: 24x36 (or slightly larger).
- Poster presentation date: Wed, Nov 2.
- Students must be at the SoC Conference Exhibit Room for poster setup & to discuss their projects with the judges at 5:00 pm on Wed, Nov 2.
- Check the website for updates.

* SDC Program is subject to change. Savant Company Inc. and the SoC Conference Organizing Committee reserve the right to revise or modify the above program at its sole discretion. Please visit the SoC Conference website for updates and changes.

QUESTIONS

Please send your questions to:
SoC@SoCconference.com or Visit the following websites:
www.SoCconference.com/students.htm
www.ieee.org/ocs



IEEE-OC Tech Job Fair

Wednesday, November 2, 2011 — 3:00 P.M. - 6:00 P.M.

Radisson Hotel Newport Beach

www.SoCconference.com/JobFair.htm

**Free Admission for Job Seekers
&
Free Parking**

Employers: You are invited to IEEE-OC Tech Job Fair if you are seeking to hire:

<ul style="list-style-type: none"> ◆ Hardware Engineers ◆ Control Systems Engineers ◆ Biomedical Engineers ◆ EDA Engineers ◆ Power Engineers ◆ Verification Engineers ◆ Layout Engineers ◆ Project Managers 	<ul style="list-style-type: none"> ◆ Software Engineers ◆ IC & IP Designers ◆ Application Engineers ◆ Manufacturing Engineer ◆ Technical Instructors ◆ Test Engineers ◆ Packaging Engineers ◆ Analog or Digital Designers 	<ul style="list-style-type: none"> ◆ Systems Engineers ◆ Sales Engineers ◆ Marketing Engineers ◆ Application Developers ◆ Web Developers ◆ Quality Engineers ◆ Project Engineers ◆ Etc . . .
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Fee:	Table Fee: \$300
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The Tech Job Fair Program Consists of:

- Free Resume Critique
- Free Mock Interviews and Job Search Counseling
- Free Pass to SoC Conference Exhibit (Going on in Parallel)
- Networking Opportunities & Much More . . .

IEEE-OC Tech Job Fair will be promoted by advertisements, IEEE OC Section and sponsoring organizations' Email lists, Newsletters, local media, etc.

SPACE IS LIMITED! TO RESERVE YOUR TABLE:

Please make checks payable to "IEEE Orange County Section" (i.e., a nonprofit organization).

**Mail Checks to:
IEEE Orange County Section
P.O. Box 15264, Irvine, CA 92623-5264**

**If you have any questions, please contact: SoC@SoCconference.com
or visit: www.SoCconference.com/JobFair.htm or www.ieee.org/ocs**

NOTE: As our contribution to the Tech Community & IEEE Members, the International System-on-Chip (SoC) Conference is providing the space for the IEEE-OC Section Tech Job Fair FREE of charge. There is absolutely no financial gain for the SoC Conference or its organizing company and affiliates. All proceeds from IEEE-OC Tech Job Fair Tables go directly to IEEE-OC Section (i.e., a nonprofit organization).



International Games Innovation Conference November 2-4, 2011

Venue

Chapman University
Orange, California USA
(Near Disneyland
and Newport Beach)

Submission Deadlines

**Power Point
Presentations and
Proposals for
Special Sessions Due:
September 1, 2011**

Two-page
Extended Abstract
Submission:
On-going

Acceptance Notice:
September 10, 2011

Final Paper
& Presentation for
Conference Proceedings:
September 20, 2011

For Submission Instructions:

<http://ice-gic.ieee-cesoc.org>

**Contact: TPC Chair
Gary Yip**
gyip.igic2011@gmail.com



Call for Presentations

The IEEE Consumer Electronics Society is pleased to announce the Third International Games Innovation Conference. This conference is a platform for disseminating peer-reviewed papers and presentations that describe innovative research and development of game technologies. Participation from industry, academia, and government is welcome.

As the Call for Papers reaches its first milestone, we are inviting submissions of presentations in power point format (~ 15 slides with abstract of ~ 200 words on 1st slide) to foster industry and government participation that describe significant, original, and on-going work. Submissions are still welcome in the previously announced format of 2-page extended abstracts that include diagrams of ideas and early results from preliminary research and development. All presentation submissions will be reviewed on the basis of their relevance, technical soundness, novelty, clarity, and overall scientific or engineering contribution. At least one presenter must attend the conference in person to be included in the Conference Program and Proceedings, IEEE Xplore and Engineering Index. Presentations reporting innovations and new developments in all areas related to games are invited, including but not limited to the following:

Multi-player Games	Platforms	Development and Production	Interfaces
Cloud based games	Mobile/handheld	Design of games	Interoperability
Networked games	Computers	Tools	Wearable devices
Location awareness	Consoles	Interdependence of Software & Hardware	Biometrics
Infrastructure	Portable consoles	Graphics	3D effects
Performance	Cloud servers	Animation	Haptics
Latency	Network servers	Content generation	Gaze
Architecture	System architecture	Artificial intelligence	Proximity
Security	Network architecture	Cinematography	Audio
			Gesture
Beyond Entertainment	User Experience	Technology	
Health/exercise	Playing experience	Multi-core processors	3D Graphics
Education/Training	Behavioral impact	Memory	3D Display
Business	Social impact	Mobile SoC	Augmented reality
Advertising	Player modeling	Virtual reality	Game mechanics
Social Change	Learning	Storage	Vision/imaging
Usability beyond games	Cultural impact	MEMS/Nano devices	Wireless/RF
	Lessons from games		

Industry Track: This conference provides an opportunity to submit power-point presentations describing design and technology challenges that should be addressed in the short-to-medium term. These presentations are encouraged for sharing of development experience, with less focus on full-paper publication.

Special Panels, Workshops and Tutorials: IGIC 2011 is planning interactive sessions (120 minutes each) in the forms of panel discussions, workshops and tutorials focusing on the latest development in game technology, including hardware, software, content development and demonstrations. Topics of discussions on future issues, especially related to innovation in game technology, are welcome.



International Games Innovation Conference November 2-4, 2011

Chapman University – City of Orange, California 92866 USA (Near Disneyland and Newport Beach)

Keynote Speakers

*Conference
Opening*



Trip Hawkins
*Founder, Electronic Arts,
3DO and Digital Chocolate*

*Reception
Banquet*



Robert J. Mical
SONY

*Award
Luncheon*



Craig Hampel
Rambus

*Conference
Closing*



Ohad Shvueli
PrimeSense

Committed Panel: Playing with Reality, Alternate Reality Games, Urban and Serious Play



Leader:
Patrícia Gouveia
Universidade Lusófona
de Humanidades
e Tecnologias

Darren O'Donnell
The Tendency
Group
Toronto, Canada

Jeff Watson
University
Southern CA
Los Angeles, CA
USA

Michael Liebe
Mediaboard
Berlin-
Brandenburg GmbH
Berlin, Germany

Flavio Escribano
ARSGAMES
Madrid-Seville,
Spain

For more information, go to <http://ice-gic.ieee-cesoc.org>, or
contact conference coordinator, Charlotte Kobert ckobert@ieee.org





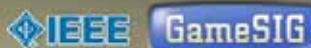
International Games Innovation Conference November 2-4, 2011

More Committed Talks:

Rambus

 **CHAPMAN
UNIVERSITY**

dmv digitalmediawire





 **IEEE**

ORANGE COUNTY SECTION

Technically Co-Sponsored by

 **IEEE
computer
society**



Tutorial Speaker:

Adrain David Cheok

**National University of
Singapore & Keio University**

Tutorial Topic:

**Culture, Learning, Play in Our Radically
Connected Era**



Panel Leader:

Tom Coughlin

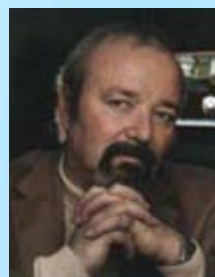
Coughlin Associates

Panel Topic:

No Storage – No Games:

The Role of Memory and Storage

Architectures in Game Design Performance



Panel Leader:

Jim Parker

University of Calgary

Panel Topic:

University Curriculum Development

Feeding the Games Industry

CPMT Society – Orange County Chapter

Short Course on Thermal Design and Modeling of IC Packages

Overview:

This short course will provide a systematic approach to the understanding of IC package-related thermal issues, thermally enhanced packages, industry standard thermal tests, IC package thermal modeling techniques, and system thermal design using IC package compact and detailed thermal models. Students completing this class should gain basic understanding of IC package thermal characteristics, improve their ability and understanding to make appropriate IC package technology selection and system design decisions, and to achieve reliable performance of complex electronic devices.

Who Should Attend:

Packaging engineers, system engineers, thermal and mechanical engineers, PCB layout engineers, field support personnel, marketing personnel, design, process, failure analysis, reliability engineers, and material scientists.

Please note class size max: 40

Location:

Building: Henkel Electronic
Materials, LLC
Room Number: Room 304
14000 Jamboree Road
Irvine, California 92606

Date: 15 November 2011

Time: 12:00PM to 05:00PM
(5.00 hours) All times are: US/Pacific

Admission Charge applies.

Register here:

<http://www.eventbrite.com/event/2189815798>

Meeting Agenda:

12:00-1:00pm: Lunch
1:00-5:00pm Short Course

Speaker:

Dr. Sam Z. Zhao of Broadcom Corporation

Topic: Thermal Design and Modeling of IC Packages

Understanding IC Package Thermal Data

- Theta-ja, Theta-jb, Theta-jc, Psi-jt

IC Package Thermal Enhancement Design

- Minimization of Theta-jc: Exposed Pad, Heat Spreader, TBGA, Flip Chip, Others
- Minimization of Theta-jb: Exposed Pad on Board, Drop-in Heat Sink, Thermal Vias, Ground Balls

JEDEC Standards for Package Thermal Characterization

- Still Air Test, Wind Tunnel Test, Theta-jb Measurement Discussion

Thermal Modeling of IC Packages

- Computational Fluid Dynamics (CFD) Based Simulations
- Heat Conduction Based Simulations
- Example of a Package Level Simulation: JEDEC Thermal Characterizations
- Example of a System Level Simulation using compact and detailed package models: Network Switching Box

Biography

Dr. Sam Z. Zhao is an Associate Technical Director at Broadcom Corporation, Irvine, CA. He received his Bachelor's and Master's degrees from Tsinghua University, Beijing, China, and his Ph.D. degree from the University of Illinois, Chicago. He did research at Cornell University in Ithaca, NY, and at the Swiss Federal Institute of Technology (ETH), Zurich in Switzerland. He has published more than 38 technical articles in peer-reviewed journals and conference proceedings. He has over 38 issued US patents.



Email: szhao@broadcom.com

Components, Packaging and Manufacturing Technology Society Orange County Chapter

Presents an All-Day Workshop on 3D Integrated Circuits: Technologies Enabling the Revolution

Date : **Friday, December 9, 2011**Location: **Jazz Semi Auditorium, [Conexant Systems, Inc. 4321 Jamboree Road, Newport Beach, CA 92660](http://www.conexant.com)**

Program Agenda

09:00 – 09:05am: Welcome & Introduction**Session – 1: Market, Architecture & Design**

09:05 – 09:35am: “Opportunities and Challenges for 3D Integrated Heterogeneous Electronic Systems” – **Prof. Muhannad Bakir, Integrated 3D Systems Group, Georgia Tech, Atlanta, GA**

09:35 – 10:05am: “Economics to Drive 3D Stacking” – **Dr. Phil Garrou, Microelectronic Consultants of North Carolina, Research Triangle Park, NC**

10:05 – 10:35am: “Stack Silicon Interconnect Development and Key Role of Supply Chain Collaboration” – **Dr. Suresh Ramalingam, Sr. Director, Xilinx, San Jose, CA**

10:35 – 10:45am: Break

10:45 – 11:15am: “Emerging Challenges for Power, Signal, and Reliability Verification on 3D-IC/Silicon Interposer Designs” – **Dr. Norman Chang, Co-Founder, Apache Design Systems, Ansys, San Jose, CA**

11:15 – 11:45am: “3D IC Test Challenges and Solutions” – **Dr. Stephen Pateras, Product Marketing Director, Silicon Test, Mentor Graphics, San Jose, CA**

11:45 – 12:15pm: “<Presentation Title to be announced>” – **A. La Manna, K. Rebibis, Dr. Eric Beyne, Dr. B. Swinnen, IMEC, Leuven, Belgium**

12:15 – 01:15pm: Lunch**Session – 2: Manufacturing Technologies & Materials**

01:15 – 01:45pm: “Cost-Effective 3D Semiconductor Packaging Solutions Based on Embedded Die in Laminate Technology” – **Ted Tessier, Senthil Sivaswamy, Flip Chip International LLC, Phoenix, AZ, Dr. Kazuhisa Itoi, Fujikura Ltd, Tokyo, Japan**

01:45 – 02:15pm: “Challenges and Solutions in Mid-end and Back-end Processes for 2.5D and 3D TSV – an OSAT Perspective” – **Dr. Yeong Lee, Product and Tech. Marketing Director, STATS ChipPAC, Fremont, CA**

02:15 – 02:45pm: “Advanced Underfills for 2.5D and 3D Applications” - **Dr. Rose Guino, Dr. Betty Huang, Dr. Kevin Becker, Dr. T. Takano, Henkel Electronic Materials, LLC, Irvine, CA**

02:45 – 03:00pm: Break

03:00 – 03:30pm: “3D TSV Interposer and its Applications” – **Dr. GS Kim, Founder & CEO, EPWorks, Ltd. Seoul, Korea**

03:30 – 04:00pm: “Via Reveal – High rate Si Thinning and Low Temperature Dielectrics for Post-TSV Processing” – **David Butler, Vice President – Marketing, SPTS Technologies, Newport, UK**

04:00 – 04:05pm: Vote of Thanks

Registrations:

Early-Bird Registration Fees: IEEE Members - \$40; Non-Members of IEEE - \$50; Students - \$20 (includes lunch & parking)

Prices will go up by \$20 for each category, after November 25, 2011.

Registration Instructions at http://meetings.vtools.ieee.org/meeting_view/list_meeting/8019

Platinum Sponsors



CONEXANT



Gold Sponsors



General Chair

Dr. Lawrence Williams, ANSYS Corporation, lwilliams@ieee.org

Technical Program

Dr. Donald Frye, Henkel Electronics Materials LLC, don3569@yahoo.com

Robert Warren, Conexant Systems, Inc. Robert.Warren@conexant.com

Sam Karikalan, Broadcom Corporation, samkarikalan@ieee.org

Vendor Exhibits:

Mark Kuhlman, Semtech Corporation, Mkuhlman@semtech.com

Workshop Organizing Committee

Publicity & Local Arrangements:

Jaydutt Joshi, Skyworks Solutions, Inc., jaydutt@gmail.com

Aaron Edwards, ANSYS Corporation, aaron.edwards@ansys.com

University Relations:

Prof. Mark Bachman, Univ. of California – Irvine, mbachman@uci.edu

Registration & Finances:

Melissa Lau, Broadcom Corporation, melissa@broadcom.com

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2011 IEEE Orange County Section — Executive Committee

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Naveen Reddy
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